

CLAIMS

Sub 21 1. A shock-resistant system for operatively interconnecting modules within a computer system to enable data to be transmitted and received therebetween comprising:

a. a first module having a first LED and a first photodiode respectively formed thereon;

b. a second module having a second LED and a second photodiode respectively formed thereon; and

10 c. wherein said first and second modules are maintained in fixed relationship to one another such that said first photodiode on said first module is operative to receive a signal produced from said second LED of said second module and said second photodiode is operative to receive signals from said first LED of said first module.

15 2. The system of Claim 1 wherein said signals generated by said first and second LEDs and received by said first and second photodiodes comprised optically transmitted infrared radiation.

3. The system of Claim 2 wherein said transmission and reception of signals between said first and second LED's and said first and second photodiodes comprise a standardized infrared communications scheme protocol.

25 ~~4. The system of Claim 3 wherein said infrared communications scheme protocol comprises a protocol developed by the Infrared Data Association.~~

Sub 22 5. ~~The system of Claim 1 wherein said first and second modules are housed within an enclosure.~~

30 Sub 23 6. ~~The system of Claim 1 wherein said first and second modules are operative to run an embedded application.~~

Sub 24 7. The system of Claim 1 wherein said system comprises a multiplicity of modules wherein each respective one of said multiplicity of modules has a dedicated LED and

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photodiode formed thereon, each respective one of said multiplicity of modules being operative to transmit and receive data via said LED and photodiode formed thereon with the respective other modules of said multiplicity of modules.

8. A method for operatively interconnecting modules within a computer to enable data to be transmitted and received therebetween comprising:

a. providing a first module having at least one first transmitter LED diode and receiver photodiode formed thereon;

b. providing a second module having a second LED and a second photodiode respectively formed thereon; and

c. spatially arranging said first module relative to said second module such that first photodiode on said first module is operative to receive a signal produced from said second LED of said second module and said second photodiode is operative to receive signals from said first LED of said first module.

9. The method of Claim 8 wherein in step c), said signals generated by said first and second LEDs and received by said first and second photodiodes comprise optically transmitted infrared radiation.

10. The method of Claim 8 wherein in step c), said transmission and reception of signals between said first and second LEDs and said first and second photodiodes comprise a standardized infrared communications scheme protocol.

11. The method of Claim 8 wherein in step c), said infrared communications scheme protocol comprises a protocol developed by the Infrared Data Association.

12. The method of Claim 8 wherein in step c), said first and second modules are housed within an enclosure.

13. The method of Claim 8 wherein in step c), said first and second circuit cards are operative to run an embedded application.

14. The method of Claim 8 wherein in step c), said
5 system comprises a multiplicity of modules wherein each
respective one of said multiplicity of modules has a
dedicated LED and photodiode formed thereon, each
respective one of said multiplicity of modules being
operative to transmit and receive data via said LED and
10 photodiode formed thereon with the respective other modules
of said multiplicity of modules.

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